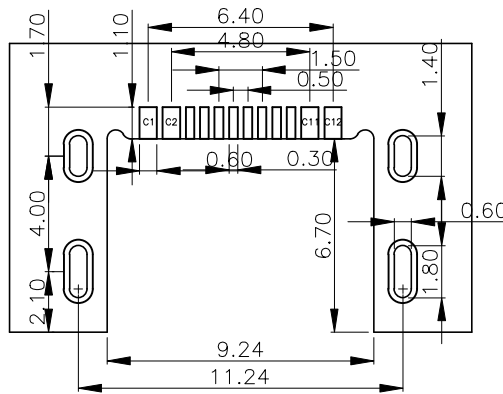
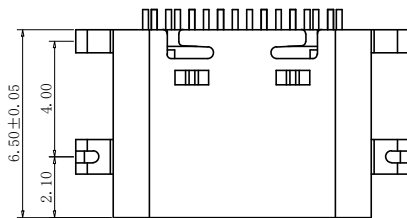
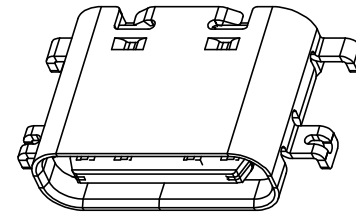
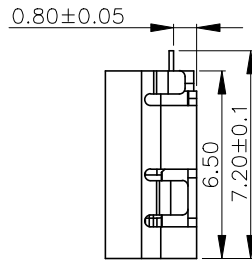
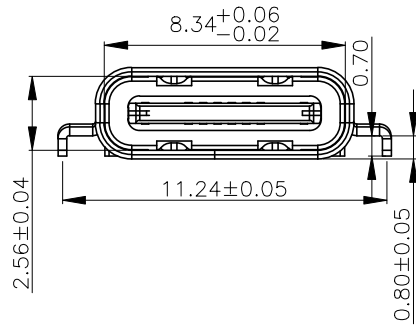




5	6		
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



PCB LAYOUT(Recommend)
(General Tolerance:±0.05)

- 1.MATERIAL SPECIFICATION:**
 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 2.CONTACTS:COPPER ALLOY
 3.MID PLATE: STAINLESS STEEL
 4.FRONT SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:**
 2-1.CONTACTS:
 Ni 40μ" MIN. UNDER PLATED OVER ALL.
 Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 (GOLD PLATING THICKNESS FOLLOW THE P/N)
 PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
- 2-2.FRONT SHELL:
 SEE TABLE1.
- 2-3.SHIELD PLATE&EMI PLATE:
 CLEAR ONLY
- 3.MECHANICAL PERFORMANCE,**
 3-1.INSERTION FORCE: 0.5~2.0N.
 3-2.REMOVAL FORCE: 0.8N~2.0N.
 3-3.DURABILITY: 10000 CYCLES.
- 4.ELECTRICAL PERFORMANCE,**
 4-1. CURRENT RATING:5.0A
 VOLTAGE RATING:5.0V
- 4-2. LLCR:
 VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX.
 SHIELD: 50mA/MAX.
 LLCR MAX. CHANGE OF ALL PINS: 10mA.
- 4-3.INSULATION RESISTANCE: 100MΩ MIN
 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
- 5. ENVIRONMENTAL PERFORMANCE:**
 OPERATING TEMPERATURE: -25°C~+85°C.
- 6.IR REFLOW:**
 THE PEAK TEMPERATURE ON THE BOARD SHALL
 BE MAINTAINED FOR 10 SECONDS AT 260°C.

16 PIN USB Type-C Receptacle Interface (Front View)

PIN NO.	A1/B12	A4/B9	B8	A5	B7	A6	A7	B6	A8	B5	B4/A9	B1/A12
SIGNAL NAME	GND	Vbus	SBU2	CC1	D-	D+	D-	D+	SBU1	CC2	Vbus	GND
PCB PAD NO.	C1	C2	C3	C4	C5	C6	C7	C8	C9	C10	C11	C12

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X. :±0.20	X° :±2°
X.X :±0.15	X.X° :±1°
X.XX :±0.10	



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	TYPE C 16pin 母座 沉板0.8(铜片)		
DWN	xiong	MC-109-C08	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
			REV: A4

CUSTOMER COPY